

## General Description

The MY2328 is the high cell density trenched N-CH MOSFET, which provides excellent  $R_{DS(ON)}$  and efficiency for most of the small power switching and load switch applications.

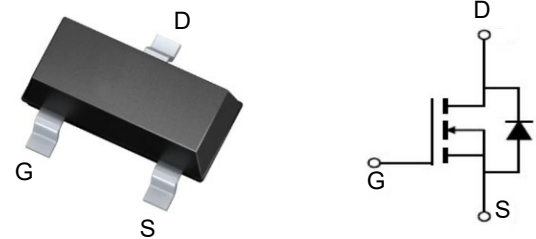


## Features

$V_{DSS}$	100	V
$I_D$	2	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	<234	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	<278	$m\Omega$

## Application

- DC/DC Converters
- Load Switch
- LED Backlighting in LCD TVs



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY2328	SOT-23	NULL	3000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	2	A
Pulsed Drain Current	$I_{DM}^*$	8	A
Maximum Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	$^\circ\text{C}$

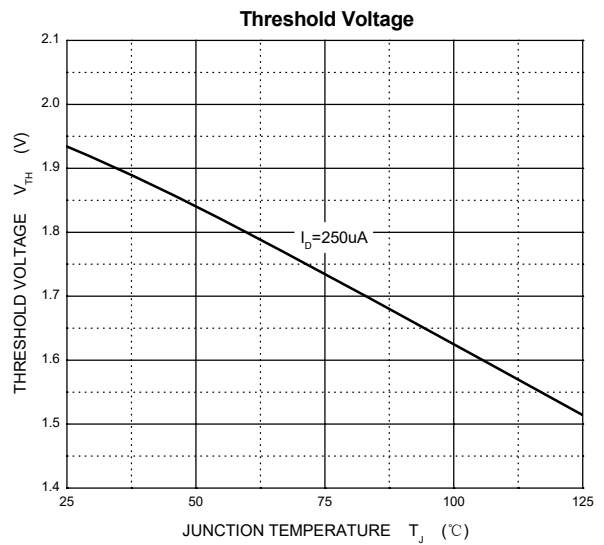
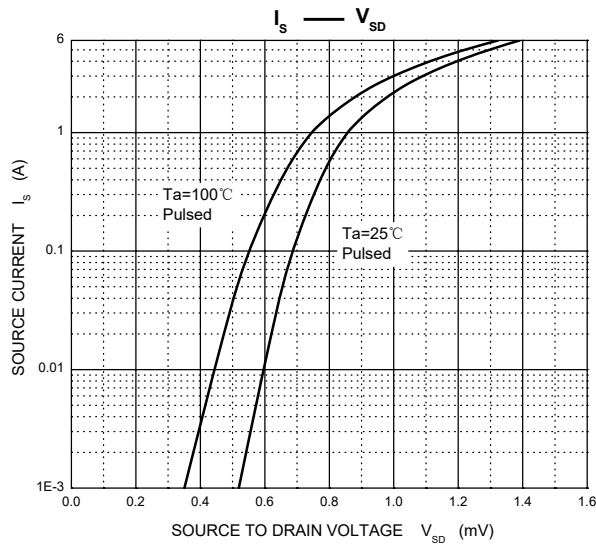
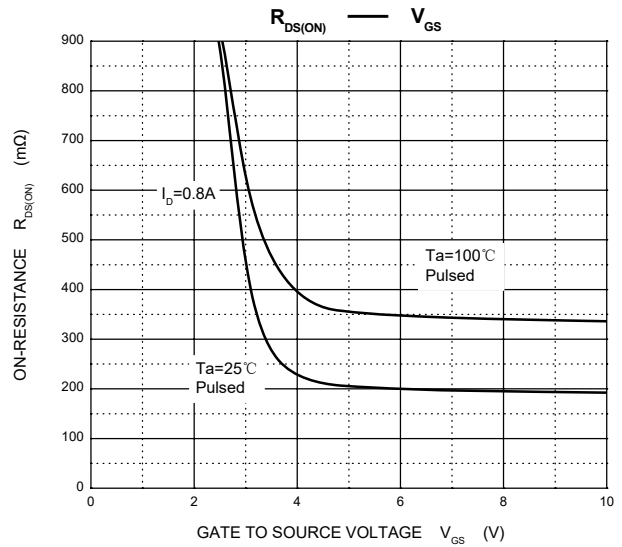
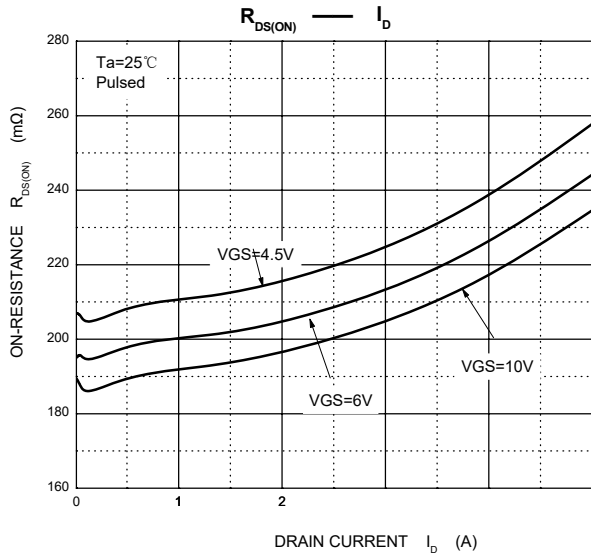
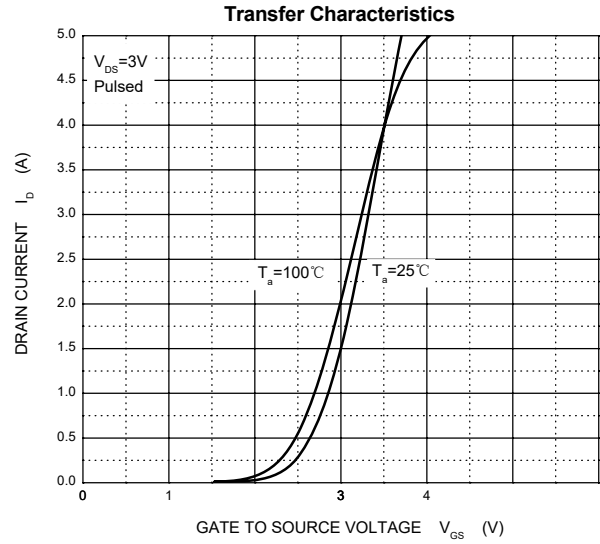
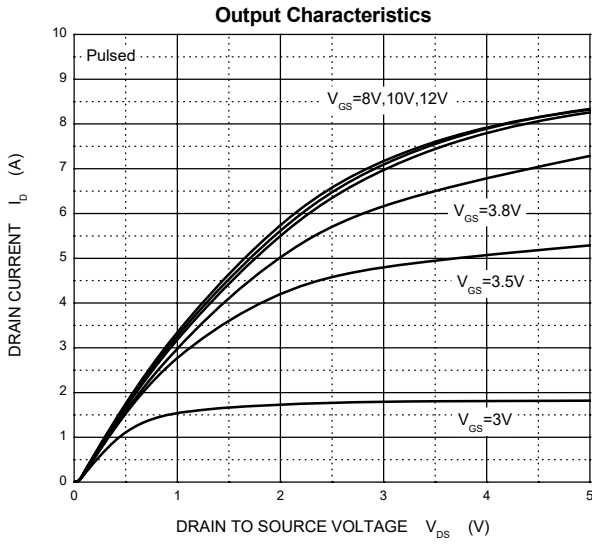
\*Repetitive rating: Pulse width limited by junction temperature.

**Electrical Characteristics (T<sub>j</sub>=25 °C, unless otherwise noted)**

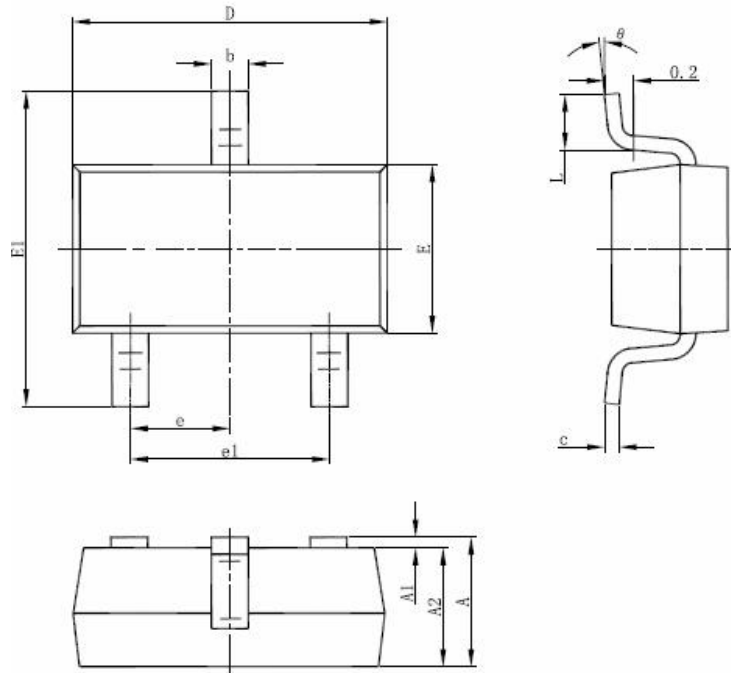
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	100			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage(note 1)	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2		2.8	V
Drain-source on-resistance (note 1)	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A			234	mΩ
		V <sub>GS</sub> =6V, I <sub>D</sub> =1A			267	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A			278	mΩ
Forward tranconductance (note 1)	g <sub>FS</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =1.5A		2		S
Diode forward voltage (note 1)	V <sub>SD</sub>	I <sub>S</sub> =1.3A, V <sub>GS</sub> = 0V			1.2	V
<b>DYNAMIC PARAMETERS (note2)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f =1MHz		190		pF
Output Capacitance	C <sub>oss</sub>			22		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			13		pF
Gate Resistance	R <sub>g</sub>	F=1MHz	0.3		2.8	Ω
<b>SWITCHING PARAMETERS (note 2)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, V <sub>GEN</sub> =4.5V R <sub>L</sub> =39Ω, R <sub>G</sub> =1Ω, I <sub>D</sub> =1.3A			45	ns
Turn-on rise time	t <sub>r</sub>				39	ns
Turn-off delay time	t <sub>d(off)</sub>				26	ns
Turn-off fall time	t <sub>f</sub>				20	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =1.6A			5.8	nC
Gate-Source Charge	Q <sub>gs</sub>			0.75		nC
Gate-Drain Charge	Q <sub>gd</sub>			1.4		nC

**Notes :** 1. Pulse Test : Pulse width≤300μs, duty cycle≤0.5%.

2. Guaranteed by design, not subject to production testing.



**Package Mechanical Data-SOT-23-3L**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°